Special Issue

Smart Manufacturing in the Era of Industry 4.0

Message from the Guest Editor

It is my immense pleasure to invite you to submit your research findings to this Special Issue, entitled “Smart Manufacturing in the Era of Industry 4.0,” of the *Journal of Manufacturing and Materials Processing,* published by MDPI. The aim of this Special Issue is to compile recent advancements and innovations in the research domains that enable smart manufacturing and the processing of materials. High-quality contributions that demonstrate substantial advancements and applications, with emphases on smart manufacturing and materials processing, will be considered for publication in this Special Issue. The desired topics of contributions include, but are not limited to, the following:

- Artificial intelligence in manufacturing and materials processing;
- Cyber-physical systems;
- Industrial robotics and automation;
- Digital transformation;
- Digital twinning;
- Additive manufacturing;
- The internet of things (IoT);
- Sensor fusion.

Guest Editor

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Deadline for manuscript submissions

closed (31 March 2025)

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About the Journal

Message from the Editor-in-Chief

Journal of Manufacturing and Materials Processing (*JMMP*)(ISSN 2504-4494) is a new MDPI peer-reviewed, open access venue with a focus on the scientific fundamentals and engineering methodologies of manufacturing and materials processing. We offer an online platform facilitating effective exchange of innovative scientific and engineering ideas and the dissemination of recent, original, and significant research and developmental findings. On behalf of the Editorial Board, I extend an invitation to our scientific and engineering colleagues to contribute high-quality, innovative, and ground-breaking research articles to *JMMP.*

Editor-in-Chief

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